ShinDengen

D3CE60VE

General Rectifying Diodes
600V, 3.5A

Feature

- Ultra-small SMD
- Ultra-thin PKG=1.0mm
- Based on AEC-Q101
- Pb free terminal
- RoHS:Yes

OUTLINE

Package (House Name): CE
Package (JEITA Code): SC-110B

Equivalent circuit

Absolute Maximum Ratings (unless otherwise specified : Tl=25°C)

Item	Symbol	Conditions	Ratings	Unit
Storage temperrature	Tstg		-55 to 150	℃
Junction temperature	Tj		-55 to 150	℃
Repetitive peak reverse voltage	V_{RRM}		600	V
Average forward current	I_F(AV)	50Hz sine wave, Resistance load, Tl=93℃	3.5	A
Average forward current	I_F(AV)	50Hz sine wave, Resistance load, Tl=103℃	3	A
Average forward current	I_F(AV)	50Hz sine wave, Resistance load, On glass-epoxy substrate, Ta=25℃ ※	1.2	A
Average forward current	I_F(AV)	50Hz sine wave, Resistance load, On glass-epoxy substrate, Ta=25℃ ※	0.8	A
Surge forward current	I_{FSM}	50Hz sine wave, Non-repetitive 1 cycle peak value, Tj=25℃	60	A
Surge forward current	I_{FSM1}	tp=1ms, sine wave, Non-repetitive, peak value, Tj=25℃	120	A

※ :See the original Specifications

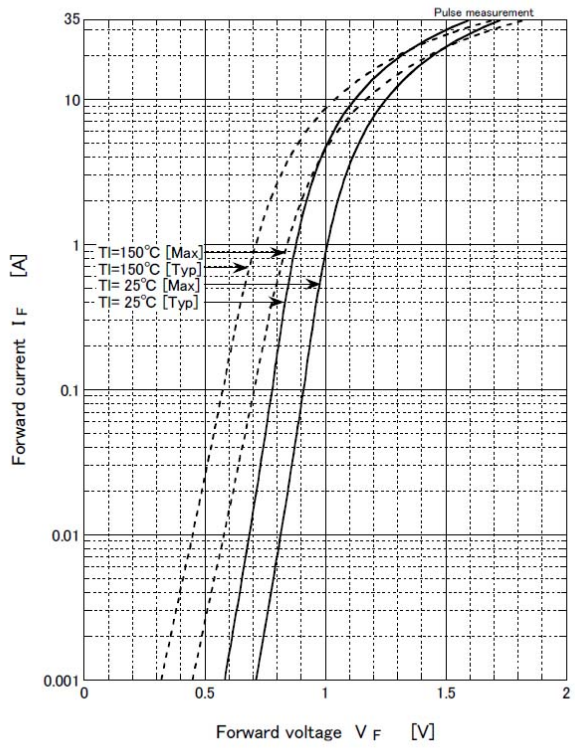
Electrical Characteristics (unless otherwise specified : Tl=25℃)

Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	
Forward voltage	V_F	IF＝3.5A, Pulse measurement			1.1	V
Reverse current	I_R	VR=600V, Pulse measurement			10	μA
Electro static dischange Capability	V_{ESD}	C=330pF, R=330Ω, Polarity±, Aerial discharge		25		kV
Thermal resistance	Rth(j-l)	Junction to lead			15	℃/W
Thermal resistance	Rth(j-a)	Junction to ambient, On glass-epoxy substrate ※			115	℃/W
Thermal resistance	Rth(j-a)	Junction to ambient, On glass-epoxy substrate ※			172	℃/W

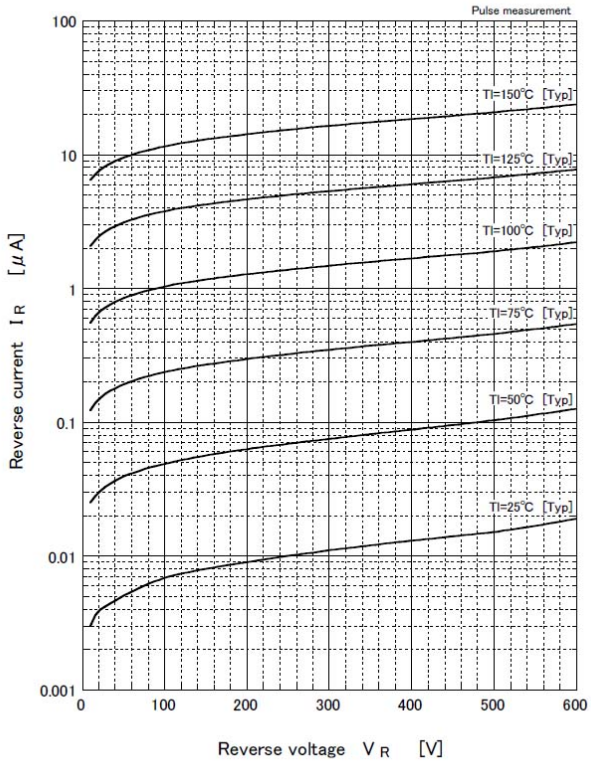
※ ：See the original Specifications

CHARACTERISTIC DIAGRAMS

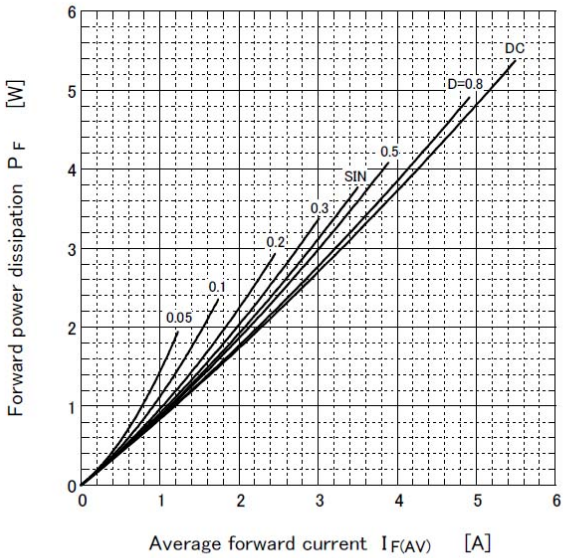
Forward voltage

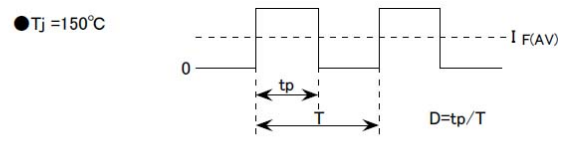


Reverse current

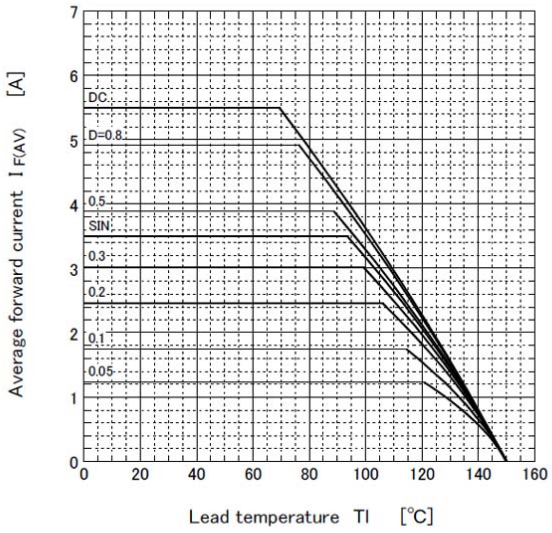


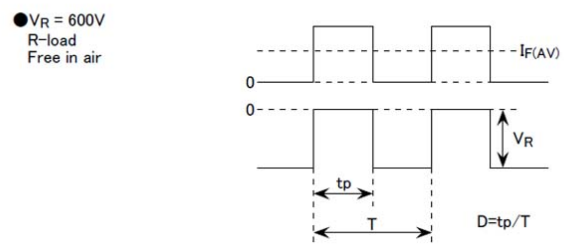
Forward power dissipation





Derating curve





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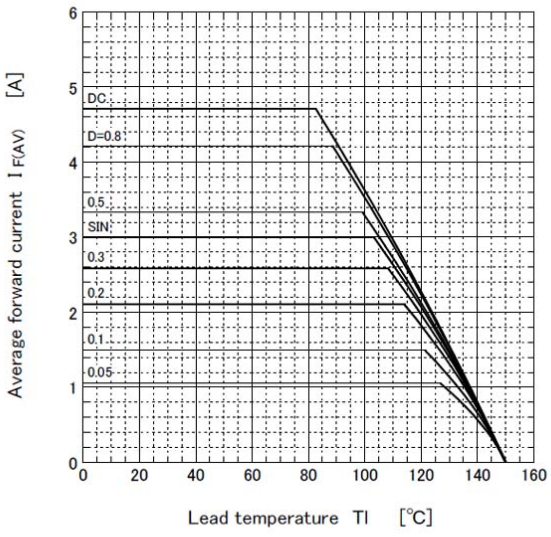
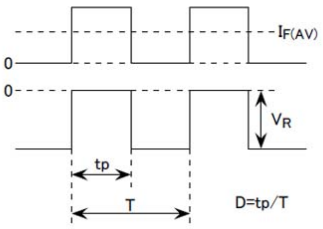


●V_R = 600V
R-load
Free in air



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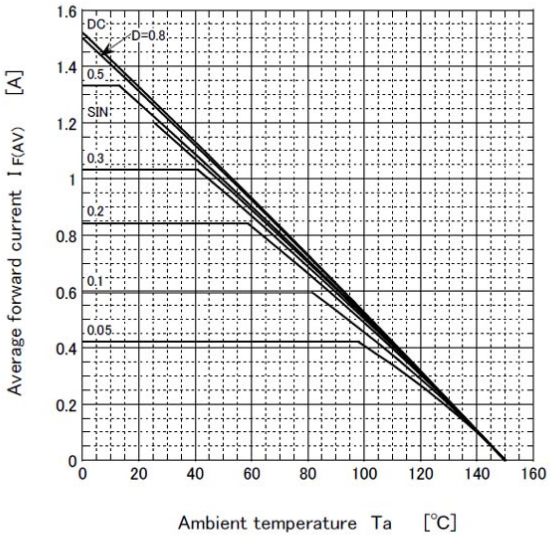
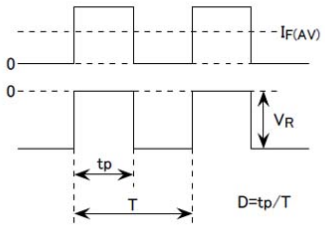


●V_R = 600V
R-load
Free in air

●Substrate detail

Type	Glass-epoxy
Size	2 inch²
Thickness	1mm
Conductor thickness	35μm
Pattern area	160mm²



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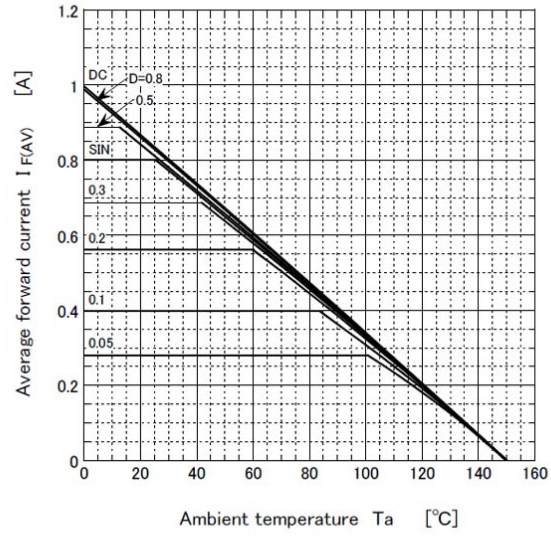

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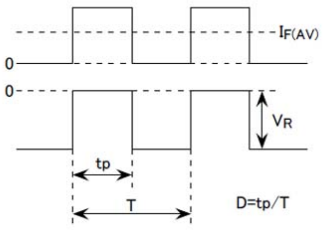
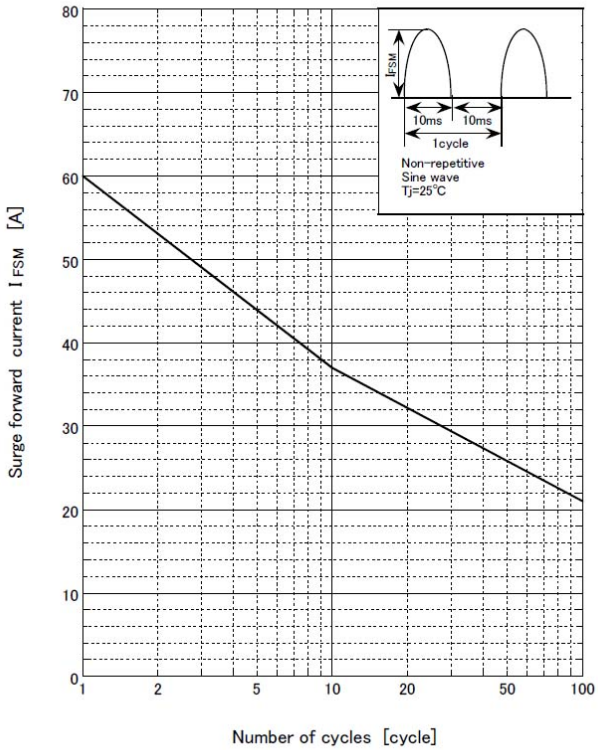


Surge forward current capability



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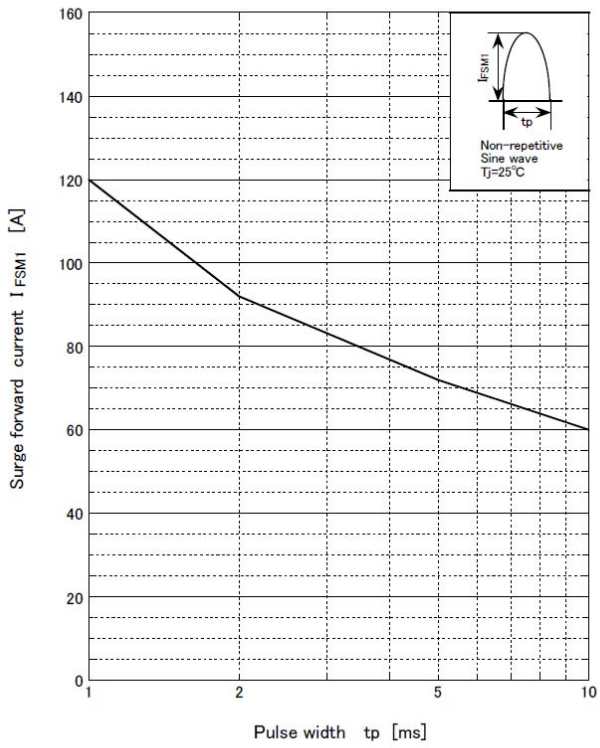
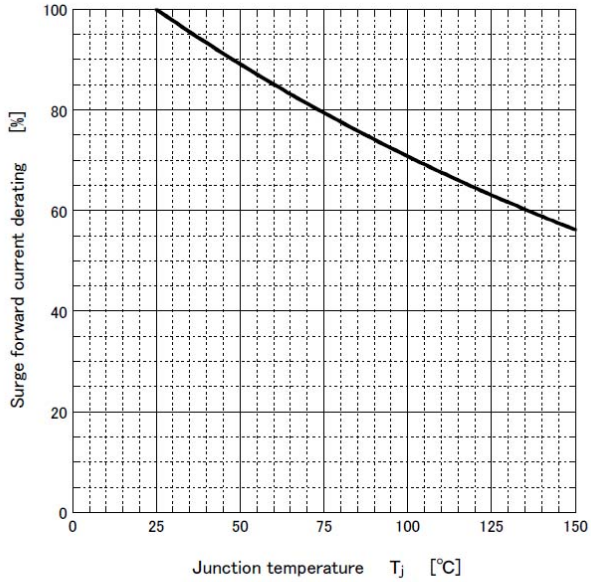
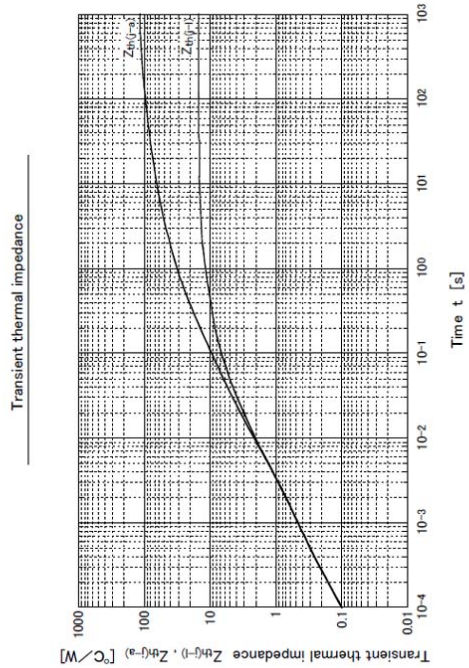


Surge forward current derating
vs Junction temperature





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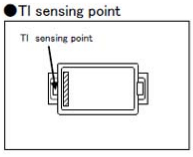
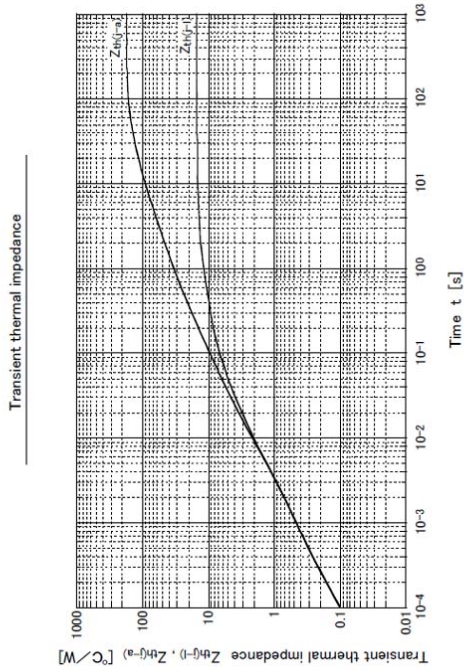
●TI sensing point





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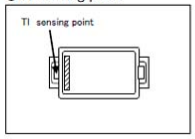


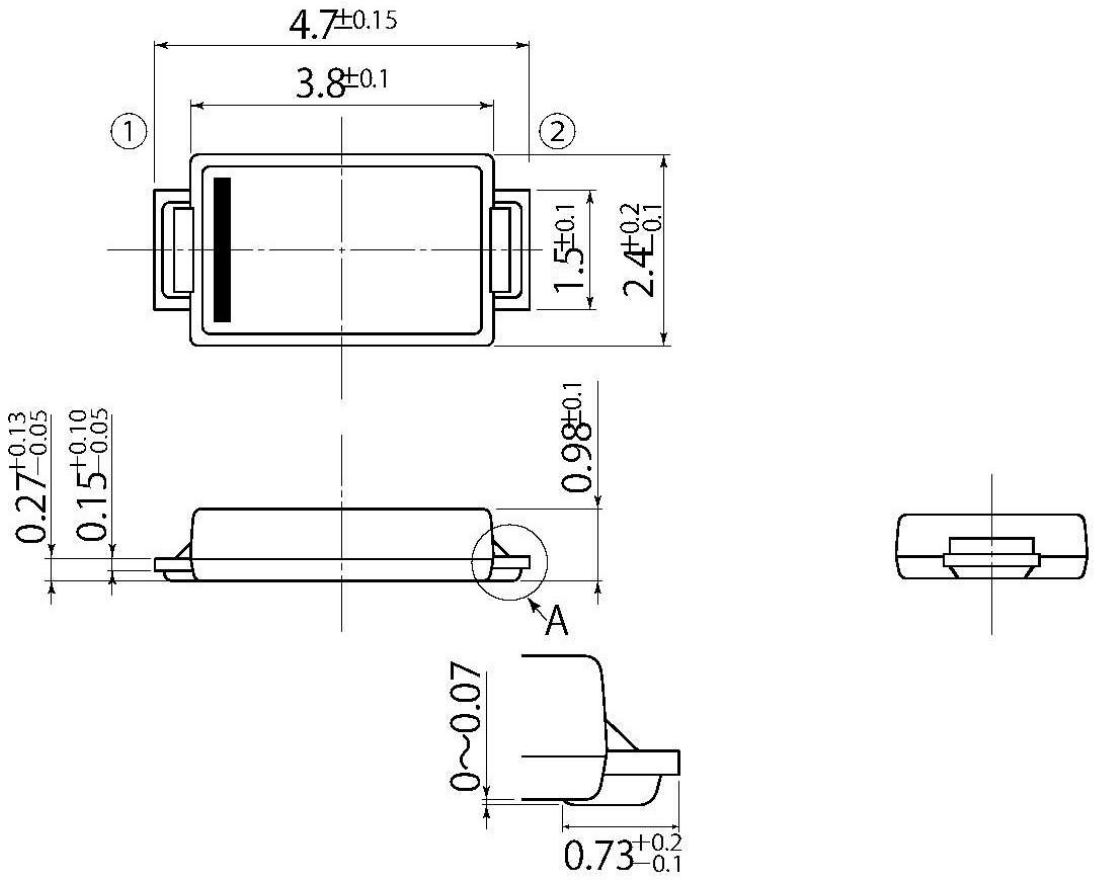
Outline Dimensions

unit:mm

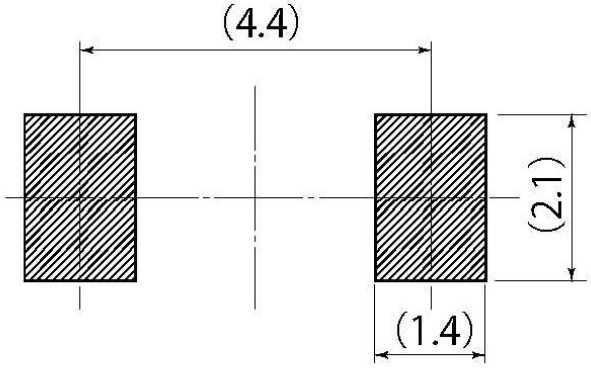
scale: 10/1

B5

JEDEC Code	–
JEITA Code	SC-110B
House Name	CE



Detail A



Referential Soldering Pad

・Optimize soldering pad to the board design and soldering condition.

Notes

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